## Product Specification

## PE42540

## Product Description

The PE42540 is a HaRPTM technology-enhanced absorptive SP4T RF switch developed on UltraCMOS ${ }^{\circledR}$ process technology. This switch is designed specifically to support the requirements of the test equipment and ATE market. It comprises four symmetric RF ports and has very high isolation. An on-chip CMOS decode logic facilitates a two-pin low voltage CMOS control interface and an optional external $\mathrm{V}_{\mathrm{SS}}$ feature. High ESD tolerance and no blocking capacitor requirements make this the ultimate in integration and ruggedness.

The PE42540 is manufactured on Peregrine's UltraCMOS process, a patented variation of silicon-oninsulator (SOI) technology on a sapphire substrate, offering the performance of GaAs with the economy and integration of conventional CMOS.

Figure 1. Functional Diagram


## UltraCMOS ${ }^{\circledR}$ SP4T RF Switch $10 \mathrm{~Hz}-8 \mathrm{GHz}$

## Features

- HaRPTM technology enhanced
- Fast settling time
- Eliminates gate and phase lag
- No drift in insertion loss and phase
- High linearity: 58 dBm IIP3
- Low insertion loss: $0.8 \mathrm{~dB} @ 3 \mathrm{GHz}$, $1.0 \mathrm{~dB} @ 6 \mathrm{GHz}$ and $1.2 \mathrm{~dB} @ 8 \mathrm{GHz}$
- High isolation: $45 \mathrm{~dB} @ 3 \mathrm{GHz}$, $39 \mathrm{~dB} @ 6 \mathrm{GHz}$ and $31 \mathrm{~dB} @ 8 \mathrm{GHz}$
- Maximum power handling: 30 dBm @ 8 GHz
- High ESD tolerance of 2 kV HBM on RFC and 1 kV HBM on all other pins

Figure 2. Package Type
32-lead $5 \times 5 \mathrm{~mm}$ LGA


Table 1. Electrical Specifications @ $+25^{\circ} \mathrm{C}, \mathrm{V}_{\mathrm{DD}}=3.3 \mathrm{~V}, \mathrm{~V}_{\mathrm{SS} \text { EXT }}=0 \mathrm{~V}\left(\mathrm{Z}_{\mathrm{S}}=\mathrm{Z}_{\mathrm{L}}=50 \Omega\right)$

| Parameter | Condition | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: |
| Operating frequency |  | $10 \mathrm{~Hz}{ }^{1}$ |  | 8 GHz |  |
| RFC-RFX insertion loss | $\begin{aligned} & 10 \mathrm{~Hz}-9 \mathrm{kHz} \\ & 3000 \mathrm{MHz} \\ & 6000 \mathrm{MHz} \\ & 7500 \mathrm{MHz} \\ & 8000 \mathrm{MHz} \end{aligned}$ |  | $\begin{aligned} & 0.7 \\ & 0.8 \\ & 1.0 \\ & 1.1 \\ & 1.2 \end{aligned}$ | $\begin{aligned} & 1.0 \\ & 1.1 \\ & 1.3 \\ & 1.5 \\ & 1.6 \end{aligned}$ | dB <br> dB <br> dB <br> dB <br> dB |
| RFX-RFX isolation | $\begin{aligned} & 10 \mathrm{~Hz}-9 \mathrm{kHz} \\ & 3000 \mathrm{MHz} \\ & 6000 \mathrm{MHz} \\ & 7500 \mathrm{MHz} \\ & 8000 \mathrm{MHz} \end{aligned}$ | $\begin{aligned} & 70 \\ & 40 \\ & 34 \\ & 27 \\ & 25 \end{aligned}$ | $\begin{aligned} & 80 \\ & 45 \\ & 39 \\ & 32 \\ & 31 \end{aligned}$ |  | dB <br> dB <br> dB <br> dB <br> dB |
| RFC-RFX isolation | $\begin{aligned} & 10 \mathrm{~Hz}-9 \mathrm{kHz} \\ & 3000 \mathrm{MHz} \\ & 6000 \mathrm{MHz} \\ & 7500 \mathrm{MHz} \\ & 8000 \mathrm{MHz} \end{aligned}$ | $\begin{aligned} & 74 \\ & 40 \\ & 28 \\ & 24 \\ & 21 \end{aligned}$ | $\begin{aligned} & 84 \\ & 45 \\ & 33 \\ & 29 \\ & 27 \end{aligned}$ |  | dB <br> dB <br> dB <br> dB <br> dB |
| Return loss (RFC to active port) | $\begin{aligned} & 10 \mathrm{~Hz}-9 \mathrm{kHz} \\ & 3000 \mathrm{MHz} \\ & 6000 \mathrm{MHz} \\ & 7500 \mathrm{MHz} \\ & 8000 \mathrm{MHz} \end{aligned}$ |  | $\begin{aligned} & 24 \\ & 23 \\ & 18 \\ & 14 \\ & 13 \end{aligned}$ |  | dB <br> dB <br> dB <br> dB <br> dB |
| Return loss (terminated port) | $\begin{aligned} & 10 \mathrm{~Hz}-9 \mathrm{kHz} \\ & 3000 \mathrm{MHz} \\ & 6000 \mathrm{MHz} \\ & 7500 \mathrm{MHz} \\ & 8000 \mathrm{MHz} \end{aligned}$ |  | $\begin{aligned} & 35 \\ & 18 \\ & 13 \\ & 11 \\ & 10 \end{aligned}$ |  | dB <br> dB <br> dB <br> dB <br> dB |
| Settling time | $50 \%$ CTRL to 0.05 dB final value ( -40 to $+85^{\circ} \mathrm{C}$ ) rising edge $50 \%$ CTRL to 0.05 dB final value ( -40 to $+85^{\circ} \mathrm{C}$ ) falling edge |  | $\begin{aligned} & 14 \\ & 15 \end{aligned}$ | $\begin{aligned} & 18 \\ & 45 \end{aligned}$ | $\begin{aligned} & \mu \mathrm{S} \\ & \mu \mathrm{~S} \end{aligned}$ |
| Switching time ( $\mathrm{T}_{\text {sw }}$ ) | $50 \%$ CTRL to $90 \%$ or $10 \%$ RF |  | 5 | 8 | $\mu \mathrm{s}$ |
| P1dB ${ }^{1}$ input 1 dB compression point RFX-RFC | All bands @ 1:1 VSWR, 100\% duty cycle | 31 | 33 |  | dBm |
| Input IP3 | 8000 MHz |  | 58 |  | dBm |
| Input IP2 | 8000 MHz |  | 100 |  | dBm |

Note 1: Maximum operating $\mathrm{P}_{\mathrm{IN}}(50 \Omega)$ is shown in Table 3. Please refer to Figure 4, Figure 5 and Figure 6 when operating the part at low frequency.

Figure 3. Pin Configuration (Top View)


Table 2. Pin Descriptions

| Pin \# | Pin Name | Description |
| :---: | :---: | :---: |
| $\begin{gathered} 1,3-6,8 \\ 9-12,14-17, \\ 19-22,24-26, \\ 28,32 \end{gathered}$ | GND | Ground |
| 2 | RF4 ${ }^{2}$ | RF I/O |
| 7 | RF2 ${ }^{2}$ | RF I/O |
| 13 | RFC ${ }^{2}$ | RF common |
| 18 | RF1 ${ }^{2}$ | RF I/O |
| 23 | RF3 ${ }^{2}$ | RF I/O |
| 27 | $V_{D D}$ | Supply |
| 29 | V1 | Switch control input, CMOS logic level |
| 30 | V2 | Switch control input, CMOS logic level |
| 31 | $\mathrm{V}_{\text {SS_ExT }}{ }^{1}$ | External V ${ }_{\text {ss }}$ negative voltage |
| Paddle | GND | Exposed solder pad: Ground for proper operation |

Notes: 1. Use $\mathrm{V}_{\text {SS_EXT }}\left(\operatorname{pin} 31, \mathrm{~V}_{\text {SS_EXT }}=-\mathrm{V}_{D D}\right)$ to bypass and disable internal negative voltage generator. Connect $\mathrm{V}_{\text {SS_EXT }}$ (pin 31) to GND
( $\mathrm{V}_{\text {SS_EXT }}=0 \mathrm{~V}$ ) to enable internal negative voltage generator.
2. All RF pins must be DC blocked with an external series capacitor or held at 0 VDC.

Table 3. Operating Ranges

| Parameter | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: |
| Supply voltage, $\mathrm{V}_{\mathrm{DD}}$ | 3.0 | 3.3 | 3.55 | V |
| Negative power supply voltage ${ }^{1}$, $\mathrm{V}_{\text {SS_EXT }}$ | -3.6 | -3.3 | -3.0 | V |
| Negative supply current, $\mathrm{I}_{\text {ss }}$ |  | -10 | -40 | $\mu \mathrm{A}$ |
| Power supply current, ID $\begin{aligned} & \mathrm{V}_{\mathrm{DD}}=3.3 \mathrm{~V}, \mathrm{~V}_{\text {SS_EXT }=0 \mathrm{~V},} \\ & \mathrm{Temp}=+85^{\circ} \mathrm{C} \end{aligned}$ |  | 90 | 160 | $\mu \mathrm{A}$ |
| Power supply current, $I_{D D}$ $\mathrm{V}_{\mathrm{DD}}=3.6 \mathrm{~V}, \mathrm{~V}_{\text {SS_EXT }} \mathrm{used}$ |  |  | 50 | $\mu \mathrm{A}$ |
| Control voltage high (V1, V2) | 1.2 | 1.5 | $V_{\text {DD }}$ | V |
| Control voltage low (V1, V2) | 0 | 0 | 0.4 | V |
| Control current, $\mathrm{I}_{\text {CTRL }}$ |  |  | 1 | $\mu \mathrm{A}$ |
| $\begin{array}{\|l} \hline \text { Pin thru path }{ }^{2}(50 \Omega, \text { RF power in }) \\ 9 \mathrm{kHz}-1 \mathrm{GHz} \\ 1 \mathrm{GHz}-8 \mathrm{GHz} \\ \left(85^{\circ} \mathrm{C}, \mathrm{~V}_{\text {SS_ExT }}=-3.0 \mathrm{~V}\right) \\ \left(85^{\circ} \mathrm{C}, \mathrm{~V}_{\text {SS_ExT }}=0.0 \mathrm{~V}\right) \\ \left(85^{\circ} \mathrm{C}, \mathrm{~V}_{\text {SS_ExT }}=-3.5 \mathrm{~V}\right) \end{array}$ |  |  | $\begin{gathered} \text { Fig. } 4-6 \\ 30 \\ 30 \\ 28 \\ 27.5 \end{gathered}$ | dBm |
| Max power into termination (50 ) $\begin{aligned} & 9 \mathrm{kHz} \leq 6 \mathrm{MHz}^{2,3} \\ & 6 \mathrm{MHz}-8 \mathrm{GHz}^{2,3} \end{aligned}$ |  |  | $\begin{gathered} \text { Fig. 4-6 } \\ 20 \end{gathered}$ | dBm |
| Max power, hot switching (50 $)$ $\begin{aligned} & 9 \mathrm{kHz} \leq 6 \mathrm{MHz}^{2,3} \\ & 6 \mathrm{MHz}-8 \mathrm{GHz}^{2,3} \end{aligned}$ |  |  | $\begin{gathered} \text { Fig. 4-6 } \\ 20 \end{gathered}$ | dBm |
| Operating temperature range, $\mathrm{T}_{\mathrm{OP}}$ | -40 |  | +85 | ${ }^{\circ} \mathrm{C}$ |

Notes: 1. Applies only when external $\mathrm{V}_{\mathrm{SS}}$ power supply is used. Otherwise, $V_{\text {SS_Ext }}=0$.
2. $100 \%$ duty cycle ( -40 to $+85^{\circ} \mathrm{C}, 1: 1$ VSWR).
3. Do not exceed 20 dBm .

Table 4. Absolute Maximum Ratings

| Parameter | Min | Max | Unit |
| :---: | :---: | :---: | :---: |
| Maximum junction temperature |  | +150 | ${ }^{\circ} \mathrm{C}$ |
| Storage temperature range, $\mathrm{T}_{\text {ST }}$ | -60 | +150 | ${ }^{\circ} \mathrm{C}$ |
| Supply voltage, $\mathrm{V}_{\mathrm{DD}}$ | -0.3 | 4 | V |
| Control voltage (V1, V2) |  | 4 | V |
| $\begin{gathered} \text { PIN }^{\text {thru path }}{ }^{2}(50 \Omega, \text { RF power in }) \\ 9 \mathrm{kHz}-1 \mathrm{GHz} \\ 1 \mathrm{GHz}-8 \mathrm{GHz} \\ \left(85^{\circ} \mathrm{C}, \mathrm{~V}_{\text {SS_EXT }}=-3.0 \mathrm{~V}\right) \\ \left(85^{\circ} \mathrm{C}, \mathrm{~V}_{\text {SSEXT }}=0.0 \mathrm{~V}\right) \\ \left(85^{\circ} \mathrm{C}, \mathrm{~V}_{\text {SS_EXT }}=-3.5 \mathrm{~V}\right) \end{gathered}$ |  | $\begin{gathered} \text { Fig. } 4-6 \\ 30 \\ 30 \\ 28 \\ 27.5 \end{gathered}$ | dBm |
| Max power into termination (50 ) $\begin{aligned} & 9 \mathrm{kHz} \leq 6 \mathrm{MHz}{ }^{1} \\ & 6 \mathrm{MHz}-8 \mathrm{GHz} \end{aligned}$ |  | $\begin{gathered} \text { Fig. 4-6 } \\ 20 \end{gathered}$ | dBm |
| ESD voltage $\mathrm{HBM}^{2}$ RFC <br> All pins |  | $\begin{aligned} & 2000 \\ & 1000 \end{aligned}$ | $\begin{aligned} & \mathrm{V} \\ & \mathrm{~V} \end{aligned}$ |
| ESD voltage CDM ${ }^{3}$, all pins |  | 450 | V |
| ESD voltage $\mathrm{MM}^{4}$, all pins |  | 100 | V |

Notes: 1. Do not exceed 20 dBm .
2. Human body model (MIL-STD 883 Method 3015).
3. Charged device model (JEDEC JESD22-C101).
4. Machine model (JEDEC JESD22-A115-A).

Exceeding absolute maximum ratings may cause permanent damage. Operation should be restricted to the limits in the Operating Ranges table. Operation between operating range maximum and absolute maximum for extended periods may reduce reliability.

## Electrostatic Discharge (ESD) Precautions

When handling this UltraCMOS device, observe the same precautions that you would use with other ESD-sensitive devices. Although this device contains circuitry to protect it from damage due to ESD, precautions should be taken to avoid exceeding the specified rating.

## Latch-Up Immunity

Unlike conventional CMOS devices, UltraCMOS devices are immune to latch-up.

## Switching Frequency

The PE42540 has a maximum 25 kHz switching rate when the internal negative voltage generator is used (pin 31 = GND). The rate at which the PE42540 can be switched is only limited to the switching time (Table 1) if an external negative supply is provided at (pin $31=\mathrm{V}_{\text {SS_ExT }}$ ).

## Optional External Vss

For proper operation, the $\mathrm{V}_{\text {SS_EXT }}$ pin must be grounded or tied to the Vss voltage specified in Table 3. When the $\mathrm{V}_{\text {SS_ExT }}$ pin is grounded, FETs in the switch are biased with an internal voltage generator. For applications that require the lowest possible spur performance, $\mathrm{V}_{\text {SS_ExT }}$ can be applied externally to bypass the internal negative voltage generator.

## Spurious Performance

The typical spurious performance of the PE42540 is -144 dBm when $\mathrm{V}_{\text {SS_Ext }}=0 \mathrm{~V}$ (pin $\left.31=\mathrm{GND}\right)$. If further improvement is desired, the internal negative voltage generator can be disabled by setting $\mathrm{V}_{\text {SS_EXT }}=-\mathrm{V}_{\mathrm{DD}}$.

Table 5. Truth Table

| State | V1 | V2 |
| :--- | :---: | :---: |
| RF1 on | 0 | 0 |
| RF2 on | 1 | 0 |
| RF3 on | 0 | 1 |
| RF4 on | 1 | 1 |

## Moisture Sensitivity Level

The moisture sensitivity level rating for the PE42540 in the 32 -lead $5 \times 5 \mathrm{~mm}$ LGA package is MSL3.

## Low Frequency Operation

Table 6 shows the minimum and maximum voltage limits when operating the device under various $\mathrm{V}_{\mathrm{DD}}$ and $\mathrm{V}_{\text {SS_EXT }}$ voltage conditions below 9 kHz . Refer to Figures 4, 5 and 6 to determine the maximum operating power over the frequency range of the device.

Table 6. Instantaneous RF Voltage Limits for Operation Below 9 kHz

| $\mathbf{V}_{\mathrm{DD}}$ | V $_{\text {SS_EXT }}$ | Minimum Peak <br> Voltage at RF Port | Maximum Peak <br> Voltage at RF Port |
| :---: | :---: | :---: | :---: |
| $\geq 3.0$ | 0.0 | -0.2 | 1.2 |
| 3.0 | -3.0 | -0.6 | 1.6 |
| 3.3 | -3.3 | -0.3 | 1.3 |
| 3.5 | -3.5 | -0.1 | 1.1 |
| 3.6 | -3.6 | 0.0 | 1.0 |

## Maximum Operating Power vs Frequency

Figures 4,5 and 6 show the power limit of the device will increase with frequency. As the frequency increases, the contours and maximum power limit will increase as shown in the curves.

## Thermal Data

Psi-JT $\left(\psi_{\mathrm{J}}\right)$, junction top-of-package, is a thermal metric to estimate junction temperature of a device on the customer application PCB (JEDEC JESD51-2).
$\psi_{J T}=\left(T_{J}-T_{T}\right) / P$
where
$\psi_{J T}=$ junction-to-top of package characterization parameter, ${ }^{\circ} \mathrm{C} / \mathrm{W}$
$\mathrm{T}_{\mathrm{J}}=$ die junction temperature, ${ }^{\circ} \mathrm{C}$
$\mathrm{T}_{\mathrm{T}}=$ package temperature (top surface, in the center), ${ }^{\circ} \mathrm{C}$
$\mathrm{P}=$ power dissipated by device, Watts

Table 7. Thermal Data for PE42540

| Parameter | Typ | Unit |
| :--- | :---: | :---: |
| $\psi_{J T}$ | 79 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
| $\Theta_{\mathrm{JA},}$ junction-to-ambient thermal resistance | 128 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |

Figure 4. Maximum Operating Power vs Frequency ( $\mathrm{T}_{\text {ambient }}=+\mathbf{2 5}^{\circ} \mathrm{C}$ )


Figure 5. Maximum Operating Power vs Frequency ( $\mathrm{T}_{\text {ambient }}=+50^{\circ} \mathrm{C}$ )


Figure 6. Maximum Operating Power vs Frequency $\left(\mathrm{T}_{\text {ambient }}=+85{ }^{\circ} \mathrm{C}\right)$


Frequency (kHz)

Figure 7. Insertion Loss vs $\mathrm{V}_{\mathrm{DD}}$
(Temp $=+25^{\circ} \mathrm{C}, \mathrm{V}_{\text {Ss_ExT }}=0$ )


Figure 9. Insertion Loss
(Temp $=+25^{\circ} \mathrm{C}, \mathrm{V}_{\mathrm{DD}}=3.3 \mathrm{~V}, \mathrm{~V}_{\mathrm{SS} \text { EXT }}=0$ )


Figure 11. Isolation: RFX-RFX vs Temp


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Figure 8. Insertion Loss vs Temp $\left(\mathrm{V}_{\mathrm{DD}}=3.3 \mathrm{~V}, \mathrm{~V}_{\mathrm{SS} \text { EXT }}=0\right)$


Figure 10. Isolation: RFX-RFX vs $\mathrm{V}_{\mathrm{DD}}$ (Temp $=+25^{\circ} \mathrm{C}, \mathrm{V}_{\text {SS_ExT }}=0$ )


Figure 12. Isolation: RFX-RFC vs $\mathrm{V}_{\mathrm{DD}}$

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Figure 13. Isolation: RFX-RFC vs Temp $\left(\mathrm{V}_{\mathrm{DD}}=3.3 \mathrm{~V}, \mathrm{~V}_{\mathrm{SS} \text { EXT }}=0\right)$


Figure 15. Active Port Return Loss vs Temp


Figure 17. Terminated Port Return Loss vs Temp


Figure 14. Active Port Return Loss vs $\mathrm{V}_{\mathrm{DD}}$ (Temp $=+25^{\circ} \mathrm{C}, \mathrm{V}_{\text {SS_Ext }}=0$ )


Figure 16. Terminated Port Return Loss vs $V_{D D}$ (Temp $=+25^{\circ} \mathrm{C}, \mathrm{V}_{\text {SS_Ext }}=0$ )


Figure 18. RFC Port Return Loss vs $V_{D D}$ (Temp $=+25^{\circ} \mathrm{C}, \mathrm{V}_{\text {SS_ExT }}=0$ )


[^0]Figure 19. RFC Port Return Loss vs Temp
$\left(\mathrm{V}_{\mathrm{DD}}=3.3 \mathrm{~V}, \mathrm{~V}_{\mathrm{SS} \text { EXT }}=0\right)$


Figure 20. Linearity Performance


## Evaluation Kit

The SP4T switch evaluation board was designed to ease customer evaluation of Peregrine's PE42540. The RF common port is connected through a $50 \Omega$ transmission line via the top SMA connector, J1. RF1, RF2, RF3 and RF4 are connected through $50 \Omega$ transmission lines via SMA connectors J2, J4, J 3 and J 5 , respectively. A through $50 \Omega$ transmission is available via SMA connectors J 6 and J7. This transmission line can be used to estimate the loss of the PCB over the environmental conditions being evaluated.

Figure 21. Evaluation Board Layout


PRT-28605

Figure 22. Evaluation Board Schematic


DOC-32927

Figure 23. Package Drawing


Figure 24. Marking Specifications


Figure 25. Tape and Reel Drawing


VEW 'A'
$\qquad$ Direction of Feed


Notes:
(I) Measured from centerline of sprocket hole to centerline of pocket.
(II) Cumulative tolerance of 10 sprocket holes is $\pm 0.20$.
(III) Measured from centerline of sprocket hole to centerline of pocket.

ALL DIMENSIONS IN MILLIMETERS UNLESS OTHERWISE STATED.
$A \mathrm{~A}=5.30 \pm 0.1 \mathrm{~mm}$
$\mathrm{Bo}=5.30 \pm 0.1 \mathrm{~mm}$
$\mathrm{Ko}=1.30 \pm 0.1 \mathrm{~mm}$
$F=5.50 \pm 0.1 \mathrm{~mm}$
$P_{1}=8.00 \pm 0.1 \mathrm{~mm}$
$W=12.00 \pm 0.3 \mathrm{~mm}$


Device Orientation in Tape

Table 8. Ordering Codes for PE42540

| Order Code | Description | Package | Shipping Method |
| :---: | :---: | :---: | :---: |
| PE42540F-Z | PE42540 SP4T RF switch | Green 32-lead $5 \times 5 \mathrm{~mm} \mathrm{LGA}$ | 3000 units/T\&R |
| EK42540-07 | PE42540 Evaluation kit | Evaluation kit | $1 / B o x$ |

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